

Message from the TPC Chairs

HOTI 2023

Welcome to the 2023 IEEE 30th Annual Symposium on High-Performance Interconnects. This conference brings together designers and architects of high-performance networks, with presentations from universities and industrial research laboratories that focus on the latest developments in leading-edge technologies. This year's conference is again entirely virtual due to the COVID-19 pandemic, representing unique challenges and opportunities for the conference program.

Our world-class team of 29 Technical Program Committee members returned insightful reviews for 16 submissions. Each paper received between three and four reviews, thus providing ample and valuable feedback to the authors, and ensuring high confidence on the outcome of the review process. Out of the 16 submissions, 8 were accepted (7 long papers and 1 short hot-topic paper).

The technical program comprises three technical sessions that cover a number of hot topics in high-performance interconnection networks. The technical paper sessions are spread across two days. The first day consists of two sessions, the first session is dedicated to interconnect standards, followed by a session on in-network optimizations. Our second day also includes two sessions, the first on smart NICs and the second on networks for large language models. Like previous years, authors of outstanding papers have been invited to deliver an extended version of their contribution to be published in a 2024 issue of IEEE Micro.

The organization of a major conference such as Hot Interconnects is a demanding and time-consuming task. We would like to thank the TPC members for their thorough reviews and active participation, despite the traditionally short review cycle of Hot Interconnects (less than one month). Owing to their dedication and promptness, Hot Interconnects is able to bring you high-quality, up-to-the-minute contributions.

We especially thank General Chairs Taylor Groves and Matthew Dosanjh for their leadership and guidance and for their enormous contributions in organizing this meeting. In addition, we would like to express our gratitude to the members of the Organizing Committee for their contributions.

Finally, and most importantly, we thank the technical paper authors, keynote and tutorial presenters, panelists, and invited talk speakers for their excellent contributions that make this event the premier international conference for high-performance interconnects.

We hope you will enjoy the symposium!

Sayan Ghosh, *Pacific Northwest National Laboratory*
Ryan Grant, *Queen's University*
Rohit Zambre, *NVIDIA*
HOTI 2023 Technical Program Chairs